

APPLICATION DATA SHEET

Inventor Information

Inventor One Given Name::	Dae Sung
Family Name::	SEO
Name Suffix::	
Postal Address Line One::	Rm. 402 Samsung Height Villa
Postal Address Line Two::	180-144 Bongcheon11-dong
City::	Gwanak-gu
State or Province::	Seoul
Country::	Korea
Postal or Zip Code	
Citizenship Country::	Korea

Correspondence Information

Correspondence Customer Number::	6449
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Application Information

Title Line One::	MICRO LEADFRAME PACKAGE HAVING OBLIQUE
Title Line One::	ETCHING
Total Drawing Sheets::	6
Formal Drawings?::	Yes
Application Type::	Utility Application
Docket Number::	1751-344
Secrecy Order in Parent Appl?::	No

Representative Information

Representative Customer Number::	6449
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Prior Foreign Applications

Foreign Application One::	2002-66122
Filing Date::	October 29, 2002
Country::	Korea
Priority Claimed::	Yes

Assignment Information

Assignee name::	SIGNETICS KOREA CO., LTD.
Street of mailing address::	483 Beopheung-ri, Tanhyun-myun
City of mailing address::	Paju-city
State or Province of mailing address::	Kyungki-do
Country of mailing address::	Korea
Postal or Zip Code of mailing address::	